

V₂O_x-Based Hole-Selective Contacts for c-Si Interdigitated Back-Contacted Solar Cells

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Gerard Masmitjà,^{*a} Luís G. Gerling,^a Pablo Ortega,^a Joaquim Puigdollers,^a Isidro Martín,^a Cristóbal Voz^a and Ramón Alcubilla^a

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Electronic Supplementary Information (ESI)

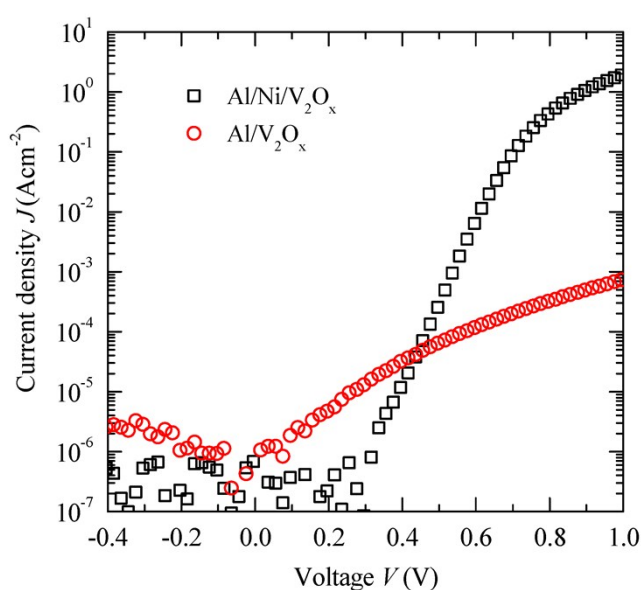


Fig. S1 Measured dark *J-V* characteristics for 40 nm thick V₂O_x on c-Si(n) diode test devices using nickel or aluminium as a capping material. The curves depict a great difference between a diode test device that utilize a Ni layer and another contacted directly with aluminium.

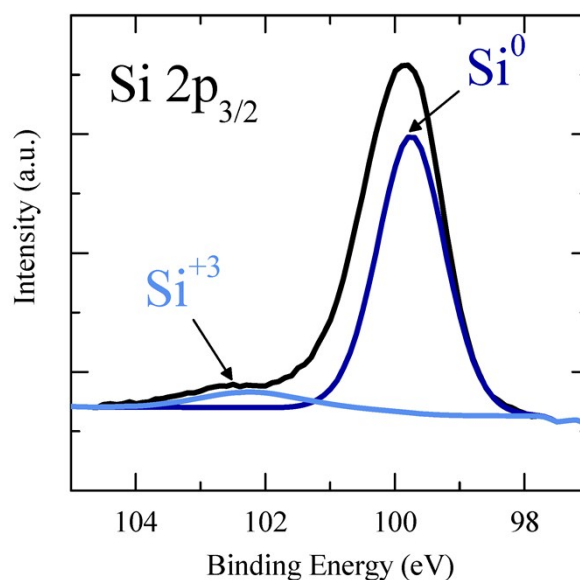


Fig. S2 XPS spectra of the Si 2p core level, showing Si⁺³ and Si⁰ oxidation states.

^a Department of Electronic Engineering, Universitat Politècnica de Catalunya (UPC),
c/ Jordi Girona 1-3, Modulo C-4, 08034 Barcelona, Spain. E-mail:
gerard.masmitja@upc.edu

† Electronic Supplementary Information (ESI) available: Additional *I-V* curve, HR-TEM image, EELS line scan. See DOI: 10.1039/x0xx00000x

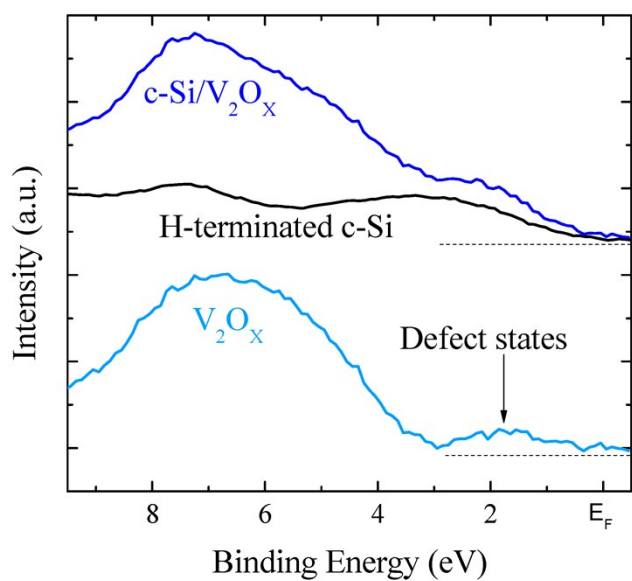


Fig. S3 Valence band spectra measured by XPS in the vicinity of the Fermi level (0 eV), where defect states are observed at ~2 eV.

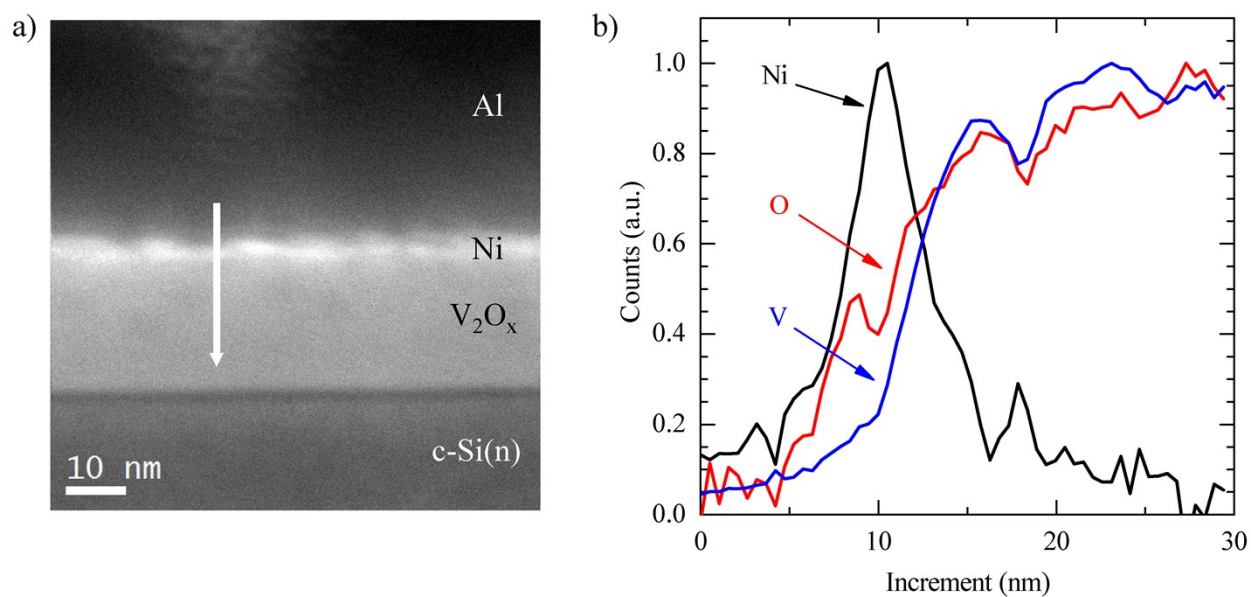


Fig. S4 **a)** High resolution transmission electron microscopy (HR-TEM) image and **b)** an electron energy loss spectroscopy (EELS) line scan across the Al/Ni/V₂O_x contact stack confirms the thin uniform nickel capping layer.